

## TRANSMITTAL

Electronic Version v1.1

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Title of Invention	ISOLATION STRUCTURES IN SEMICONDUCTOR INTEGRATED CIRCUITS (IC)							
<p>Application Number :</p> <p>Date :</p> <p>First Named Applicant:        Brent A. Anderson</p> <p>Confirmation Number:</p> <p>Attorney Docket Number:        BUR920040170US1</p>								
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<table border="1"><thead><tr><th data-bbox="133 1010 773 1050">Submitted By:</th><th data-bbox="773 1010 1112 1050">Elec. Sign.</th><th data-bbox="1112 1010 1414 1050">Sign. Capacity</th></tr></thead><tbody><tr><td data-bbox="133 1050 773 1125">William D. Sabo Registered Number: 27465</td><td data-bbox="773 1050 1112 1125">/William D. SABO, Reg 27465/</td><td data-bbox="1112 1050 1414 1125">Attorney</td></tr></tbody></table>			Submitted By:	Elec. Sign.	Sign. Capacity	William D. Sabo Registered Number: 27465	/William D. SABO, Reg 27465/	Attorney
Submitted By:	Elec. Sign.	Sign. Capacity						
William D. Sabo Registered Number: 27465	/William D. SABO, Reg 27465/	Attorney						

Documents being submitted:	Files
us-fee-sheet	BUR920040170US1-usfees.xml us-fee-sheet.xsl us-fee-sheet.dtd
us-ids	BUR920040170US1-usidst.xml us-ids.dtd us-ids.xsl
us-assignment	BUR920040170US1-usassn.xml us-assignment.xsl us-assignment.dtd BUR920040170Assign1.tif BUR920040170Assign2.tif
us-request	BUR920040170US1-usrequ.xml us-request.dtd us-request.xsl
application-body	BUR920040170ABX.xml application-body.dtd Image1.tif Image2.tif isoamsa.ent isoamsb.ent isoamsc.ent isoamsn.ent isoamso.ent isoamsr.ent isobox.ent isocyr1.ent isocyr2.ent isodia.ent isogr1.ent isogr2.ent isogr3.ent isogr4.ent isolat1.ent isolat2.ent isomfrk.ent isomopf.ent isomscr.ent isonum.ent isopub.ent isotech.ent mathml2.dtd mathml2-qname-1.mod mmlalias.ent mmlextra.ent soextblx.dtd us-application-body.xsl wipo.ent
application-body-pdf-wrap	BUR920040170ABX-pdf-wrap.xml
abstract-pdf	BUR920040170ABX-abst.pdf

claims-pdf	BUR920040170ABX-clms.pdf
description-pdf	BUR920040170ABX-desc.pdf
drawings-pdf	BUR920040170ABX-draw.pdf
us-declaration	BUR920040170dec1.tif
us-declaration	BUR920040170dec2.tif
<b>Comments</b>	
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